

ICSICT 2018

International Conference on Solid-State and Integrated Circuit Technology

Oct.31-Nov.3, 2018

Huangdao Sheraton Hotel,
Qingdao, China

<http://www.icsict.com>

FIRST CALL FOR PAPERS

The ICSICT-2018 conference is the 14th in the series aiming to provide an international forum for the presentation and discussion of recent advances in solid-state and integrated circuit technology. The conference will be held on Oct.31-Nov.3, 2018 in Qingdao, China. All aspects of solid-state devices, circuits, processing technologies, materials and other related research are within the scope of the conference. The three days of contributed and invited presentations on the latest developments in diverse fields given in oral and poster sessions, panel discussions on leading edge technology issues, and other activities will provide extensive opportunities for technical information exchange as well as a stimulating environment for mutual communication among participants. Excellent Student Paper Award will be presented at the closing of the conference.

THE SCOPE AND TOPICS OF THE CONFERENCE

(Papers are solicited in, but not limited to the following areas)

VLSI Technologies

1. Channel Engineering
2. High-k/Metal gate Technology
3. Advanced Source/Drain Technology
4. Interconnect Technology
5. Advanced 3D Integration
6. Novel Process Technologies
7. Ultra-Thin Body Transistors
8. High Performance CMOS Platforms
9. CMOS Like Novel Devices
10. Advanced FinFETs and Nanowire FETs
11. CNT, MTJ Devices and Nanowire Devices
12. Low- Power and Steep Slope Switching Devices
13. 2D Devices & Technologies
14. Advanced Technologies for Ge MOSFETs
15. Organic semiconductor devices and technologies
16. Compound semiconductor devices and Technology
17. Ultra High Speed Transistors, HEMT/HBT etc.
18. Photoelectron Devices
19. Advanced Power Devices and Reliability
20. Flash Memory
21. IT Magnetic RAM

22. Resistive RAMs
 23. Phase Change Memory
 24. 3-Dimensional Memory
 25. MEMS Technology
 26. Thin Film Transistors
 27. Sensors
 28. PV and Energy Harvesting
 29. Front End of Line (FEOL) Reliability
 30. Memory Reliability
 31. Back-End of Line and ESD Reliability
 32. Device Simulation & Modeling
 33. Process Simulation & Modeling
 34. Artificial Intelligence (Process & Device)
 35. Internet of Things (Process & Device)
- VLSI Circuits & ICCAD**
36. Processors
 37. Analog Circuits
 38. SOC
 39. PLL and CDR
 40. Low-Power Nyquist ADCs
 41. Digital Circuits Resilient
 42. High-Resolution and High Speed Data Converters
 43. Digital Chip-to-Chip and On-Die Interfaces
 44. Advanced Clock
 45. Artificial Intelligence (Circuits & System)
 46. Internet of Things (Circuits & System)
 47. FPGA
 48. Memory Circuits
 49. Advanced Transceivers Techniques
 50. EDA
 51. RF Circuits and Systems
 52. Interference Robust RF Receivers
 53. Signal Processing
 54. System-Level Modeling & Simulation/Verification
 55. System-Level Synthesis & Optimization
 56. High-Level/Behavioral/Logic Synthesis & Optimization
 57. Physical Design
 58. DFM

PAPER SUBMISSION

Prospective authors are requested to submit **3 pages** camera-ready full length paper in English for proceedings publication. The proceedings will have an IEEE catalogue number and will be collected in IEEE publication database ---- IEEE X'plore®.

Deadline for Camera-Ready Full-Length Paper Submission: June 30, 2018.

Notification of Acceptance: Aug. 15, 2018

On-line submission at web-site <http://www.icsict.com> is required.

About paper submission, please contact:

Dr. Yu-Long Jiang
School of Microelectronics
Fudan University
Shanghai 200433, China
E-mail: ylijang@fudan.edu.cn
Tel:+86-21-65643768; Fax:+86-21-65643768

ICSICT 2018 ORGANIZATIONS

Name	Affiliation	Country /Area
Life Honorary Chair		
Yangyuan Wang	Peking University	China
General Co-Chairs		
Cor Claeys	IMEC	Belgium
Bin Zhao	Fairchild	USA
Ting-Ao Tang	Fudan University	China
Advisory Committee Co-Chairs		
Ru Huang	Peking University	China
Chenming Hu	UC Berkeley	USA
T.C. Chen	IBM	USA
K.N.Tu	UCLA	USA
Technical Program Committee Co-Chairs		
Yu-Long Jiang	Fudan University	China
Hiroshi Iwai	Tokyo Institute of Technology	Japan
J. J. Liou	University of Central Florida	USA
Jason Woo	UCLA	USA
Yong Lian	York University	UK
Yi Zhao	Zhejiang University	China
Ming Li	Peking University	China
Organizing Committee Co-Chairs		
Mengqi Zhou	IEEE Beijing Section	China
Huihua Yu	Fudan University	China
Publicity Chair		
Secretary General		
Fan Ye	Fudan University	China

Sponsored by  **IEEE** Beijing Section

Co-Sponsored by Fudan University



Patrons by

